



Material Content Data Sheet



Sales Product Name		BFP 640ESD H6327		Issued		26. January 2016		
MA#		MA000796164						
Package		PG-SOT343-4-2		Weight*		6.93 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.003	0.04		393	
	non noble metal	tin	7440-31-5	0.001	0.01		101	
	inorganic material	silicon	7440-21-3	0.024	0.34	0.39	3429	3923
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		497	
	non noble metal	chromium	7440-47-3	0.010	0.15		1492	
	non noble metal	copper	7440-50-8	3.433	49.53	49.74	495270	497359
wire	noble metal	gold	7440-57-5	0.011	0.16	0.16	1585	1585
encapsulation	organic material	carbon black	1333-86-4	0.030	0.44		4368	
	plastics	epoxy resin	-	0.651	9.39		93919	
	inorganic material	silicondioxide	60676-86-0	2.347	33.85	43.68	338546	436833
leadfinish	non noble metal	tin	7440-31-5	0.202	2.91	2.91	29101	29101
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31199	31199
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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